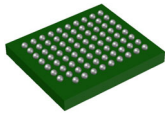
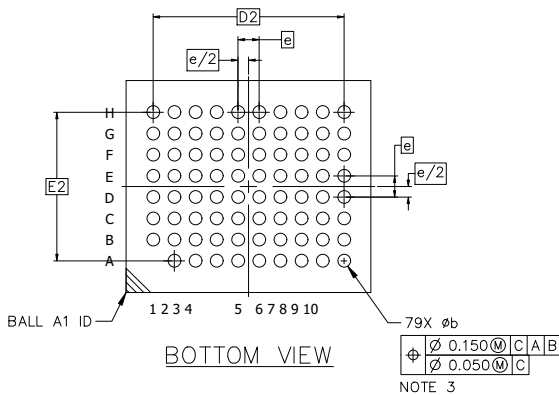
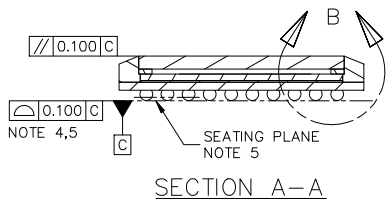
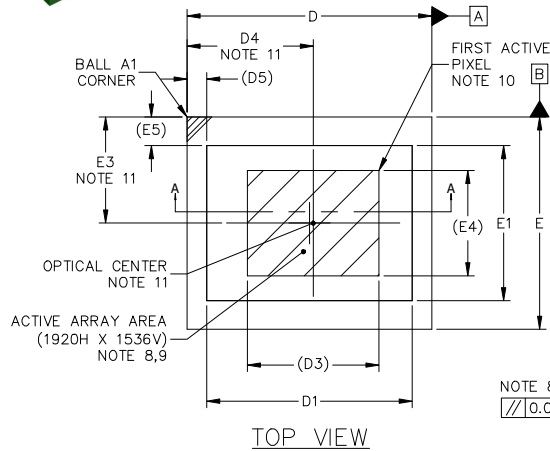


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

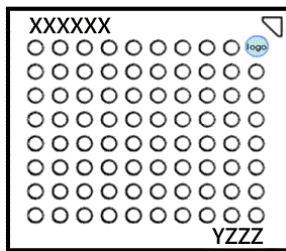


## IBGA79 7.50x6.50x1.05, 0.65P CASE 503CS ISSUE B

DATE 07 FEB 2024



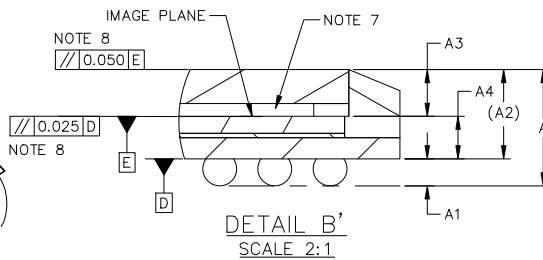
### GENERIC MARKING DIAGRAM\*



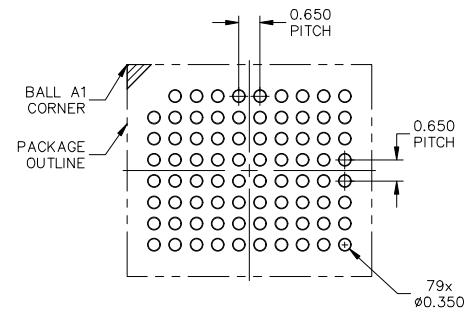
XXXX = Specific Device Code  
Y = Year  
ZZZ = Lot Traceability

#### NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.150 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ± 0.5°.
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.115, 0.000)
- PACKAGE CENTER (X, Y) = (0.000, 0.000).



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.550
A1	0.270	0.320	0.370
A2	1.050 REF.		
A3	0.500	0.550	0.600
A4	0.450	0.500	0.550
b	0.350	0.400	0.450
D	7.425	7.500	7.575
D1	6.200	6.300	6.400
D2	5.850 BSC		
D3	4.032 REF.		
D4	3.790	3.865	3.940
D5	0.600 REF.		
E	6.425	6.500	6.575
E1	4.660	4.760	4.860
E2	4.550 BSC		
E3	3.175	3.250	3.325
E4	3.226 REF.		
E5	0.870 REF.		
e	0.650 BSC		



### RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>IBGA79 7.50x6.50x1.05, 0.65P</b>	<b>PAGE 1 OF 1</b>

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